Figure 1: Photograph of inside cover

Figure 2: Photograph of circuit board assembled on base (1)

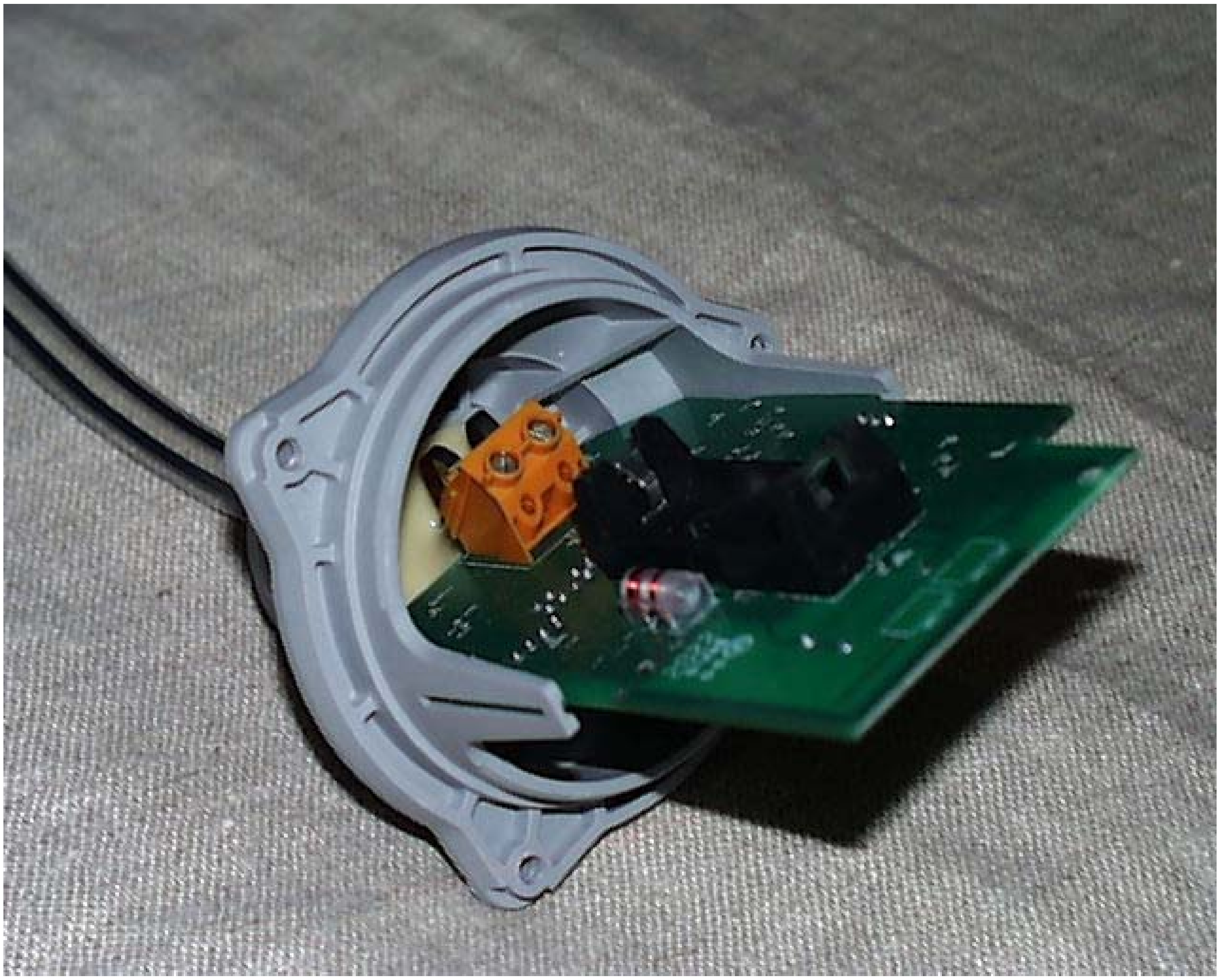

Figure 3: Photograph of circuit board assembled on base (2)

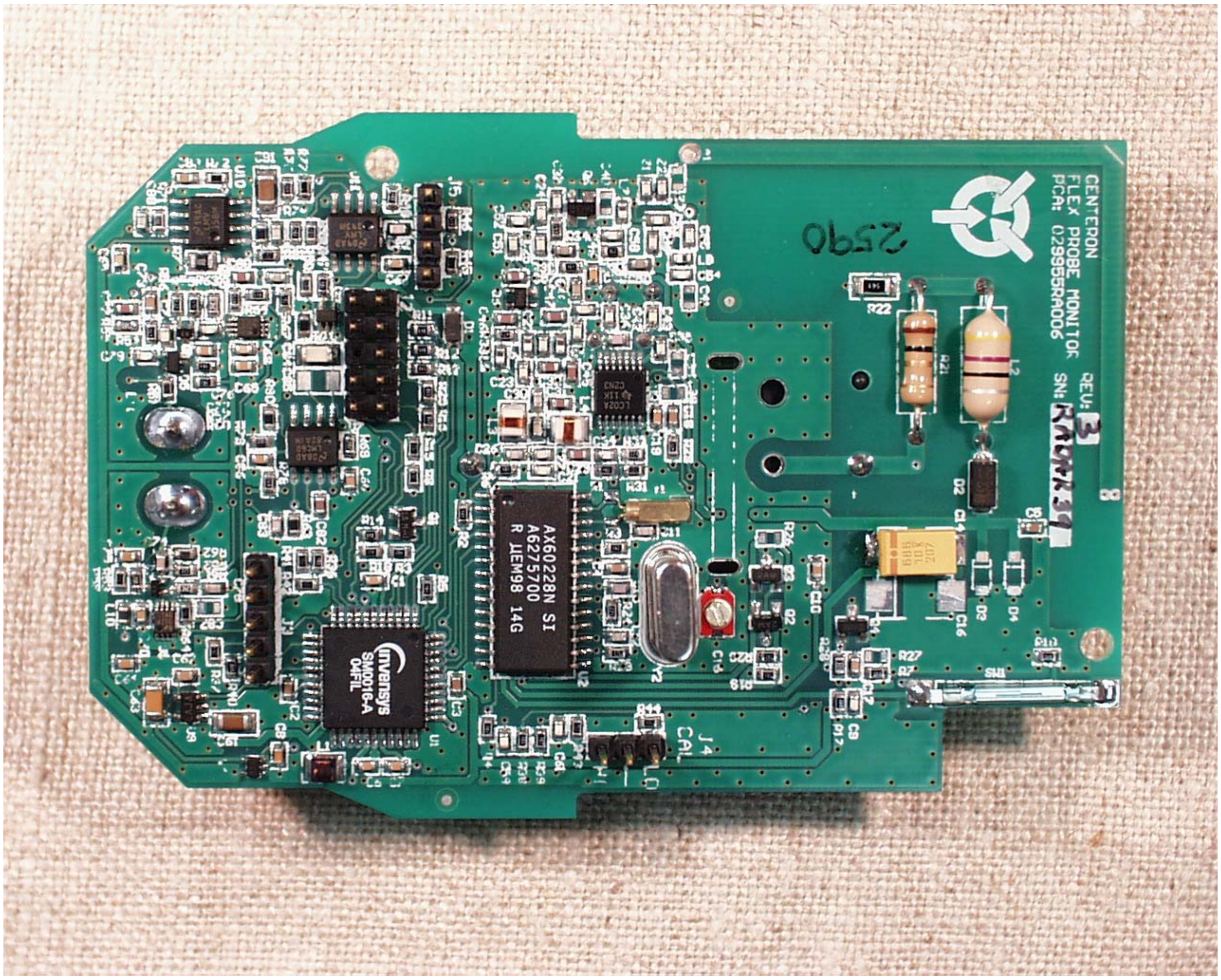

Figure 4: Photograph of component side of device under test

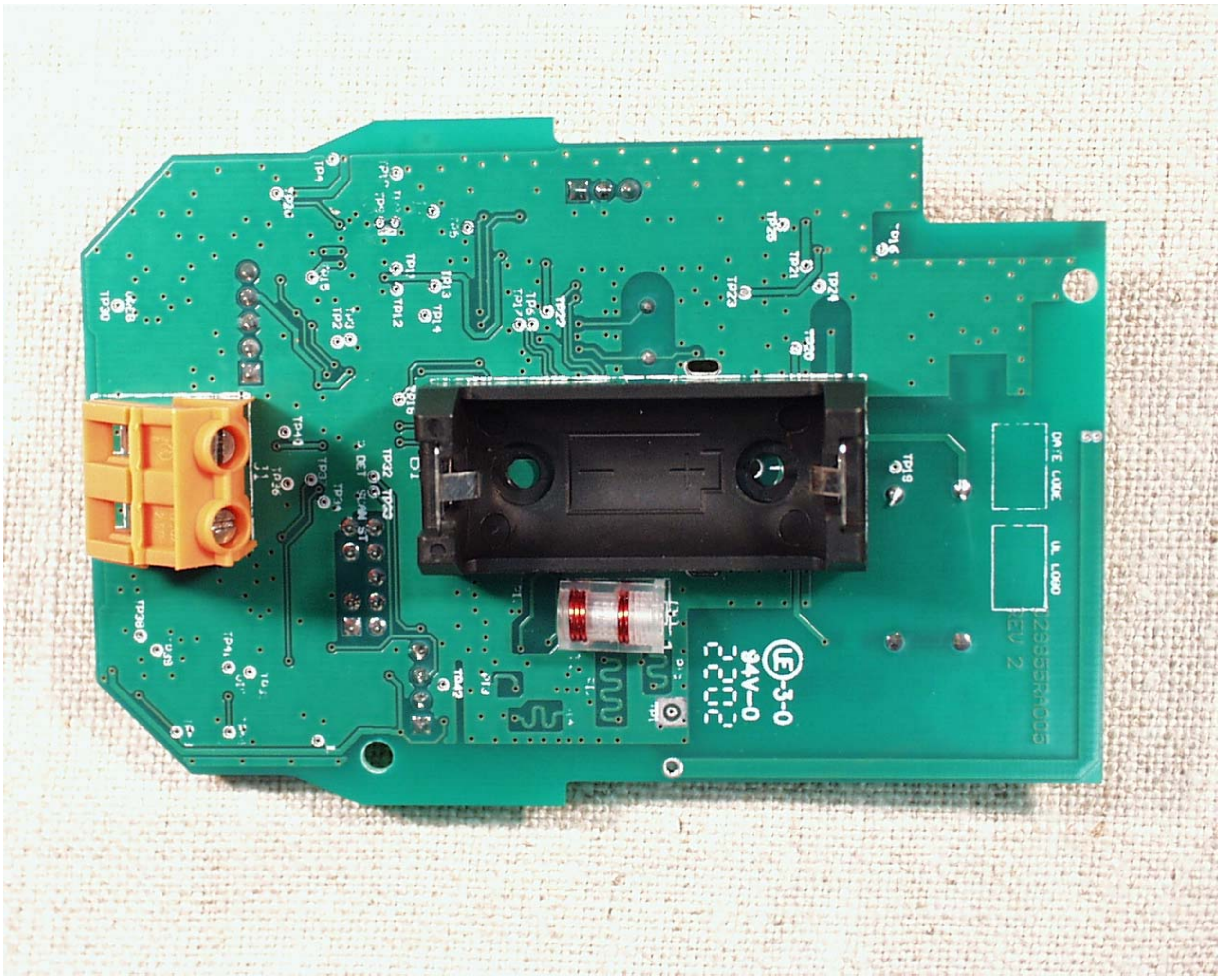

Figure 5: Photograph of solder side of device under test